

PATENT ASSIGNMENT

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CONVEYING PARTY DATA	
Name	Execution Date
Yuya OHNISHI	04/24/2009
RECEIVING PARTY DATA	
Name:	SHARP KABUSHIKI KAISHA
Street Address:	22-22, Nagike-cho, Abeno-ku
City:	Osaka-shi, Osaka
State/Country:	JAPAN
Postal Code:	545-8522
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12466681
CORRESPONDENCE DATA	
Fax Number:	(703)816-4100
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	703-816-4000
Email:	teh@nixonvan.com
Correspondent Name:	NIXON & VANDERHYE, PC
Address Line 1:	901 NORTH GLEBE ROAD, 11TH FLOOR
Address Line 4:	ARLINGTON, VIRGINIA 22203
ATTORNEY DOCKET NUMBER:	1035-868
NAME OF SUBMITTER:	H. Warren Burnam, Jr.
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OP \$40.00 12466681

ASSIGNMENT OF PATENT APPLICATION

(Inventors) Yuya OHNISHI

(Assignee)
(Address)
(Other Countries)
(Title)

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to SHARP KABUSHIKI KAISHA of 22-22 Nagaike-cho Abeno-ku Osaka-shi Osaka 545-8522 Japan, (hereinafter designated as the Assignee) the undersigned's entire right, title and interest for the United States, its territories, dependencies and possessions, and for the country of in the invention, and all application(s) for patent and any Letters Patent which may be granted therefor, known as SEMICONDUCTOR DEVICE, METHOD FOR MOUNTING SEMICONDUCTOR DEVICE, AND MOUNTING STRUCTURE OF SEMICONDUCTOR DEVICE (Case No. -) for which the undersigned has (have) executed on even date herewith an application for patent in the United States of America or, if not on even date, then has executed on or has already filed in U.S. appln. Serial No. filed on The undersigned acknowledges an obligation of assignment of this invention to said assignee at the time the invention was made.

The undersigned agree(s) to execute all papers and documents necessary in connection with the application or any interference which may be declared and any continuing or divisional applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient and further to perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patent of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the firm of NIXON & VANDERHYE P.C. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document. It is understood and agreed that ASSIGNEE'S attorneys Nixon & Vanderhye P.C. have represented only ASSIGNEE and will continue to represent only ASSIGNEE with respect to this invention.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned signature(s).

Date ~~2009/4/24~~^{Y.O}
April 24, 2009

Signature of inventor

Yuya Ohnishi
Yuya OHNISHI

Date _____ Signature of inventor

Date _____ Signature of inventor

Date _____ Signature of inventor

Date _____ Signature of inventor

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